

Form 1449*	Atty. Docket No.: 303.444US5	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Scott G. Meikle et al.	
	Filing Date: Herewith	Group: Unknown

U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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JP	Patent Abstracts of Japan, vol 18, no. 684 (E-1650), 22.12.94 & JP-A-6275776 (30.09.94),
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	Lahav, et al., "Measurement of thermal expansion coefficients of W, Wsi, WN and Wsin thin film metallizations", <u>J. Appl. Phys.</u> , 67 (2), 734-738, (January, 1990)
	Nakajima, et al., "Preparation of Tungsten Nitride Film by CVD Method Using WF6", <u>J. Electrochem. Soc.: SOLID STATE SCIENCE AND TECHNOLOGY</u> , Vol. 134, No. 12, 3175-3178, (December, 1987)

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